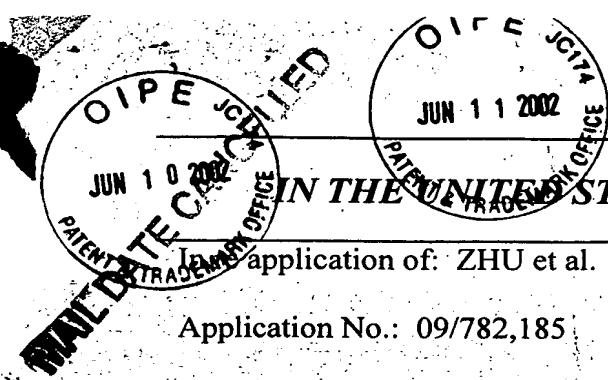


1765
PATENT

application of: ZHU et al.

Application No.: 09/782,185

Filed: February 12, 2001

Title: UNIQUE PROCESS CHEMISTRY FOR
ETCHING ORGANIC LOW-K MATERIALS

Attorney Docket No.: LAM1P147/P0675

Examiner: CHEN, Kin-Chan

Group: 1765

COPY OF PAPERS
ORIGINALLY FILED**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Box Non-Fee Amendment, Commissioner for Patents, Washington, D.C. 20231 on May 16, 2002.

Signed:

Sue Funchess

Sue Funchess

AMENDMENT A TRANSMITTAL

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

The fee has been calculated as shown below.

	Claims After Amendment		Highest Previously Paid For	Present Extra	Small Entity Rate Fee	Large Entity Rate Fee
Total Claims	16	MINUS	20	0	x 9 =	x 18 = \$-0-
Independent Claims	2	MINUS	3	0	x 42 =	x 84 = \$-0-
Multiple Dependent Claim Present and Fee Not Previously Paid					\$140.00	\$280.00
				Total	\$	\$-0-

- Applicant(s) hereby petition for a _____ month extension(s) of time to respond to the aforementioned Office Action.
- Applicant(s) believe that no (additional) Extension of Time is required; however, if it is determined that such an extension is required, Applicant(s) hereby petition that such an extension be granted and authorize the Commissioner to charge the required fees for an Extension of Time under 37 CFR 1.136 to Deposit Account No. 50-0388 (Order No. LAM1P147).
- Enclosed is our Check No. _____ in the amount of \$_____ to cover the additional claim fee and/or extension of time fees.
- Please charge the required fees, or any additional fees required to facilitate filing the enclosed response, to Deposit Account No. 50-0388 (Order No. LAM1P147).

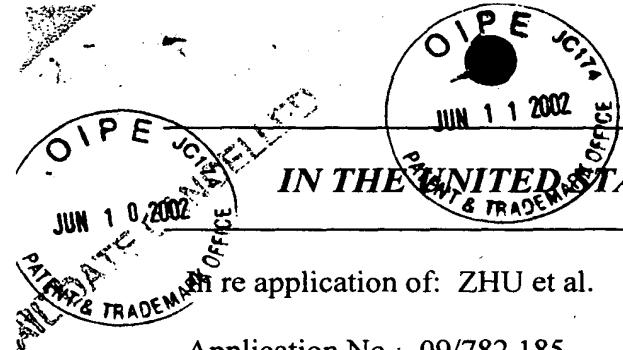
Respectfully submitted,
BEYER WEAVER & THOMAS, LLP

Michael Lee

Michael Lee
Reg. No. 31,846

P.O. Box 778
Berkeley, CA 94704-0778

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

JUN 10 2002

PATENT & TRADEMARK OFFICE

In re application of: ZHU et al.

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Signed: Sue Funchess
Sue Funchess

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated February 26, 2002, please amend the above-identified patent application as follows:

In the Claims:

Please cancel claims 5 and 7 and amend claims 1, 2, 6, and 8-10 as follows:

1. (Once Amended) A method for etching a feature in an integrated circuit wafer, the wafer incorporating at least one silicon-free low-k dielectric layer, the method comprising:
disposing the wafer within a reaction chamber;
introducing a flow of fluorocarbon-containing etchant gas into the reaction chamber;
forming a plasma from the etchant gas within the reaction chamber; and
etching the feature in at least a portion of the silicon-free low-k dielectric layer.

2. (Once Amended) The method, as recited in claim 1, wherein the silicon-free low-k dielectric layer is an organic silicon-free benzocyclobutene low-k dielectric layer.

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